

ABSTRACT OF THE DISCLOSURE

[53] The invention is based on a method and an apparatus for scanning a semiconductor wafer (1), on-the-fly images of regions on the wafer being acquired using a camera (3). Upon a scan line changeover, a continuously curved displacement track is generated by at least partial superimposition of the relative motions between the wafer (1) and camera (3) in the direction of the scan lines and perpendicular thereto. As a result, time is saved and wafer throughput is increased.